

Issue	Cover Story			Trend & Analysis						Design & Technology				Specials*	
				China Focus*	Design Trends	Opinions	Interview	Building Blocks	Analog Equipment	Engineers' Blog*	Design Corner	Test & Measurement	China Fables*		Teardown
January <i>Booking deadline: November 20</i>	Technology Outlook 2016			China IC Industry	•	•	•	•	•	•	•	- Energy Harvesting - New User Interface - DAC/ADC	Oscilloscope	•	
February <i>Booking deadline: December 18</i>	Advanced Semiconductor Technology/EDA	IP	Simulation/Signal Integrity		•	•	•	•	•	•	•	- LED Lighting - Auto Electronics - MPU	Signal Generator	•	
March <i>Booking deadline: January 15</i>	Industry 4.0 (Internet+)	Distributed Computing	Communication Security	Tech Shanghai 2016	•	•	•	•	•	•	•	- Timer/Clock - Power Design - ADC/Amplifier	Mixed-signal Test	•	Smart Devices Microwave China
April <i>Booking deadline: February 22</i>	AR/VR/Games	GPU Technology	Human-machine Interface		•	•	•	•	•	•	•	- Embedded Design - MEMS Sensor - Location Technology	Wireless System Test	•	
May <i>Booking deadline: March 21</i>	Smart Home/ Security/IoT	Image Processing	Sensor Technology	Biometrics	•	•	•	•	•	•	•	- Motor Control - EMI/EMC - Wireless Connect Technology	EMI Test	•	Power Greater China IC Design
June <i>Booking deadline: April 20</i>	Intelligent Hardware/ Wearable/Health Care	Wireless Communication	Low-power Consumption Processing		•	•	•	•	•	•	•	- PCB Design - Wearable Device Design - EDA/IP	Testing Software/IP	•	Microwave China
July <i>Booking deadline: May 20</i>	RF/Wireless	Energy Harvesting	NFC	Advanced Technology for MEMS	•	•	•	•	•	•	•	- Digital Signal Processing - Smart Grid - Medical Electronics	Modularized Testing Instrument	•	
August <i>Booking deadline: June 20</i>	Smart Phone	CPU/Memory Technology	Interface & Peripheral Chip Technology		•	•	•	•	•	•	•	- Photoelectricity & Display - Power Management - RF/Microwave	Vector Signal Analyzer	•	
September <i>Booking deadline: July 20</i>	Robot/UAV	Network Protocol	MCU/Processor		•	•	•	•	•	•	•	- FPGA/DSP - Audio Design - Low-power Design	Power Test	•	Microwave China
October <i>Booking deadline: August 19</i>	Auto Electronics	In-vehicle Network	Power Device	Tech Shenzhen 2016	•	•	•	•	•	•	•	- Database Security and Encryption - Memory Technology - Digital Power	High-speed Serial Test	•	IoT
November <i>Booking deadline: September 16</i>	5G Communication	MIMO System	SDN/Cloud	New Energy/ Smart Grid	•	•	•	•	•	•	•	- Open Source Hardware - Touch Technology - Mobile Graphics Processor	Embedded System Test	•	Maker
December <i>Booking deadline: October 20</i>	Medical Electronics	Specific Processor	Signal Acquisition		•	•	•	•	•	•	•	- IGBT/MOSFET - Security Monitoring - Microcontroller	Communication Test	•	Microwave China

Remark: * for China edition only.

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